

Product Compliance Declaration

Please see www.molex.com for the most up-to-date information.

Contact Information

Name Molex Product Compliance E-Mail Product.Compliance@molex.com

Part Information

Part Number 5016471000 Part Weight 0.076G

Part Name 2.0 W/B Dual Grid Rcpt Crmp TerChn

Product Composition

Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)	
2.0 W/B Dual Grid Rcpt Crmp TerChn	Component		100	0.076	
Copper-Nickel-Silicon	Material		100	0.076	
Copper-Nickel-Silcon Unplated	Material		98.75	0.07505	
Silicon	Substance	7440-21-3	0.5431	0.000413	
Zinc (metal)	Substance	7440-66-6	1.3331	0.001013	
Tin	Substance	7440-31-5	0.2962	0.000225	
Copper	Substance	7440-50-8	95.1456	0.072311	
Nickel	Substance	7440-02-0	1.4319	0.001088	
Tin Plating	Material		0.66	0.000502	
Tin	Substance	7440-31-5	0.66	0.000502	
Nickel Plating	Material		0.39	0.000296	
Nickel	Substance	7440-02-0	0.39	0.000296	
Further Additives, not to declare	Substance	system	4E-05	3E-08	

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Limitation of this Product Compliance Declaration: This declaration is based on the state of knowledge and belief of Molex as of the date that it is provided. Molex bases its knowledge and belief on information provided by numerous sources, including third parties, and in certain circumstances laboratory test results. Molex has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and substances. Molex represents that to the best of its knowledge that the information provided in this declaration is accurate. Molex's sole liability shall be to either replace the product or refund the purchase price of the product if it does not meet the requirement of this declaration.

Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)
Copper Plating	Material		0.2	0.000152
Copper	Substance	7440-50-8	0.2	0.000152

ROHS Declaration Information

Regulatory Revision EU 2015/863

Compliance Status Compliant

Contained Substances Exceeding Threshold

None

Exemptions

None

REACH-SVHC Declaration Information

Regulatory Revision D(2020)9139-DC (19 Jan 2021)

Contained Substances Exceeding Threshold

None

GADSL Declaration Information

Regulatory Revision GADSL imported from IMDS

Contained Substances Exceeding Threshold

Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
lead	Silicon Bronze	*Note	103.82	Yes
lead	e-plate Sn (electrodeposited Tin Coatings, bright and matt)	*Note	500	Yes
nickel powder [particle diameter < 1 mm]	Silicon Bronze	*Note	14,900.62	Yes
nickel powder [particle diameter < 1 mm]	Ep-Ni	*Note	997,500	Yes
copper	Silicon Bronze	*Note	963,549.25	Yes

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Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
copper	e-plate Cu (electrodeposited Copper Coatings)	*Note	999,625	Yes

^{*}Note: For GADSL substance declarable/prohibited threshold values, please reference http://www.gadsl.org/

Exemptions

Part Name	Exemption
Silicon Bronze	44 Concentration within acceptable GADSL limits
e-plate Sn (electrodeposited Tin Coatings, bright and matt)	44 Concentration within acceptable GADSL limits
Silicon Bronze	34 Not applicable
Ep-Ni	33 Other application (Surface not routinely touched or nickel release rate < 0.5µg/cm2/week)

HFLH Declaration Information

Regulatory Revision IEC 61249-2-21

Contained Substances Exceeding Threshold

None

China ROHS Declaration Information

Part Number	5016471000							
Part Name	2.0 W/B Dual Grid Rcpt Crmp TerChn	(e)						
Part Information	on			Haz	zardous S	Substance	s	
Components			Lead	Mercury	Cadmium	Hex. Chromium	PBB	PBDE
2.0 W/B Dual	Grid Rcpt Crmp TerChn		0	0	0	0	0	0

Process Information

Component Plating / Surface Finish	N/A
Termination Base Alloy	N/A
Solder Alloy	N/A

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Process Capability	N/A
Maximum Exposure Time (seconds)	N/A
Maximum Process Temperature (C)	N/A
Maximum Cycles at Reflow Temperature	N/A
J-STD-020 Moisture Sensitivity Level	N/A

Mar 9, 2021